


[illegible]

Examination and allowance of pending claims 1-3 are respectfully requested.

WEBB ZIESENHEIM LOGSDON  
ORKIN & HANSON, P.C.

  
Kent E. Baldauf  
Registration No. 25,826

Kent E. Baldauf  
Registration No. 25,826  
Attorney for Applicants  
700 Koppers Building  
436 Seventh Avenue  
Pittsburgh, PA 15219-1818  
Telephone: 412-471-8815  
Facsimile: 412-471-4094

## MARKED-UP AMENDED SPECIFICATION PARAGRAPH

### Page 1, title

[PROCESS FOR PRODUCING CARD]  
CARDS

PROCESS FOR PRODUCING

### Page 1, first complete paragraph

The present invention relates generally to a process for producing IC (integrated circuit) cards. More particularly, the present invention relates to a process for producing cards, which can avoid exposure, on the card surface, of unevennesses of components such as IC chips, capacitors and antenna coils mounted or formed on a mount substrate.

### Page 4, first section heading

[DISCLOSURE OF THE INVENTION]

SUMMARY OF THE INVENTION

### Page 6, first section heading

[BRIEF DESCRIPTION OF THE DRAWING]

BRIEF DESCRIPTION OF THE  
DRAWINGS

### Page 7, first section heading

[BEST MODE FOR CARRYING OUT THE INVENTION] DETAILED  
DESCRIPTION OF THE INVENTION

### Page 9, second complete paragraph

Further, an adhesive 28, 30 in fluid condition [28, 30] is fed over respective surfaces 20A, 22A of the sheet members 20, 22 delivered from the sheet member supply rolls 16, 18 through adhesive supply means 32, 35 such as die coaters or T-dies.

[illegible]